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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	AVR
Core Size	8-Bit
Speed	16MHz
Connectivity	EBI/EMI, I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	86
Program Memory Size	64KB (32K x 16)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TFBGA
Supplier Device Package	100-CBGA (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atmega640-16cu

Figure 1-2. CBGA-pinout ATmega640/1280/2560

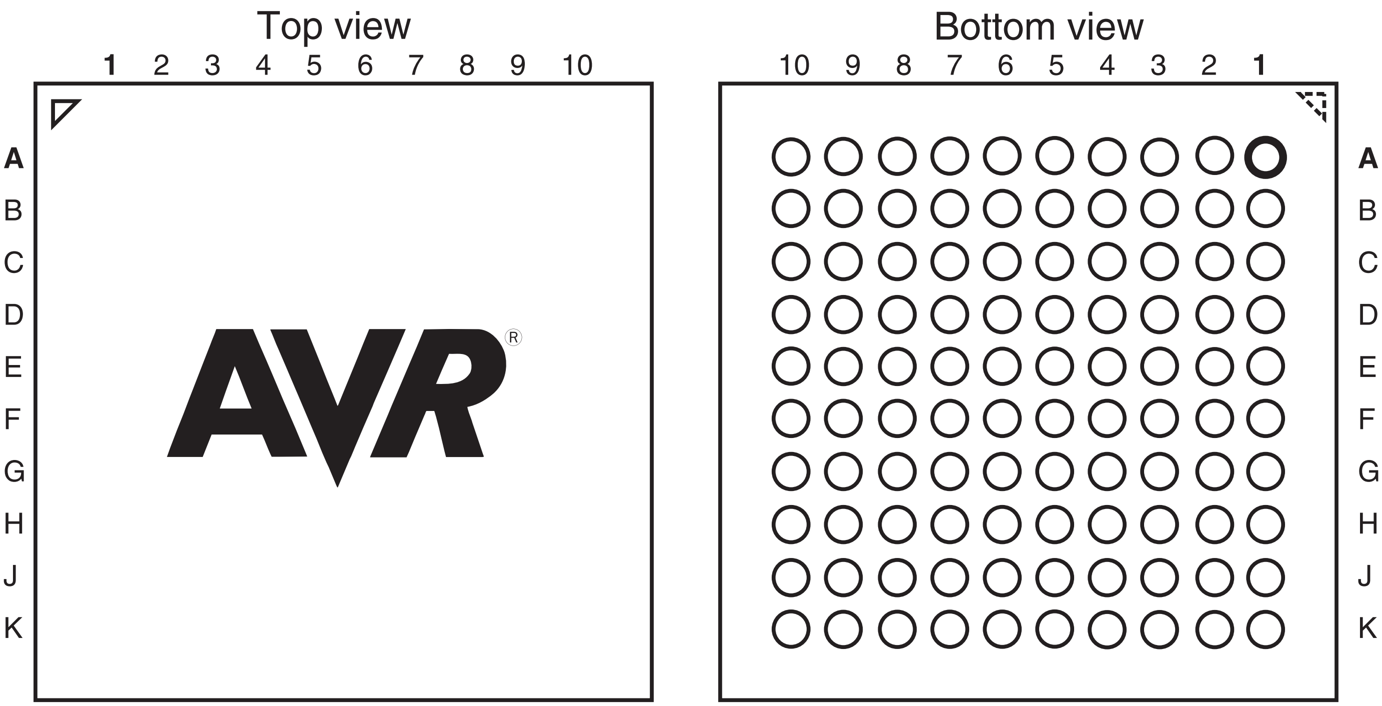
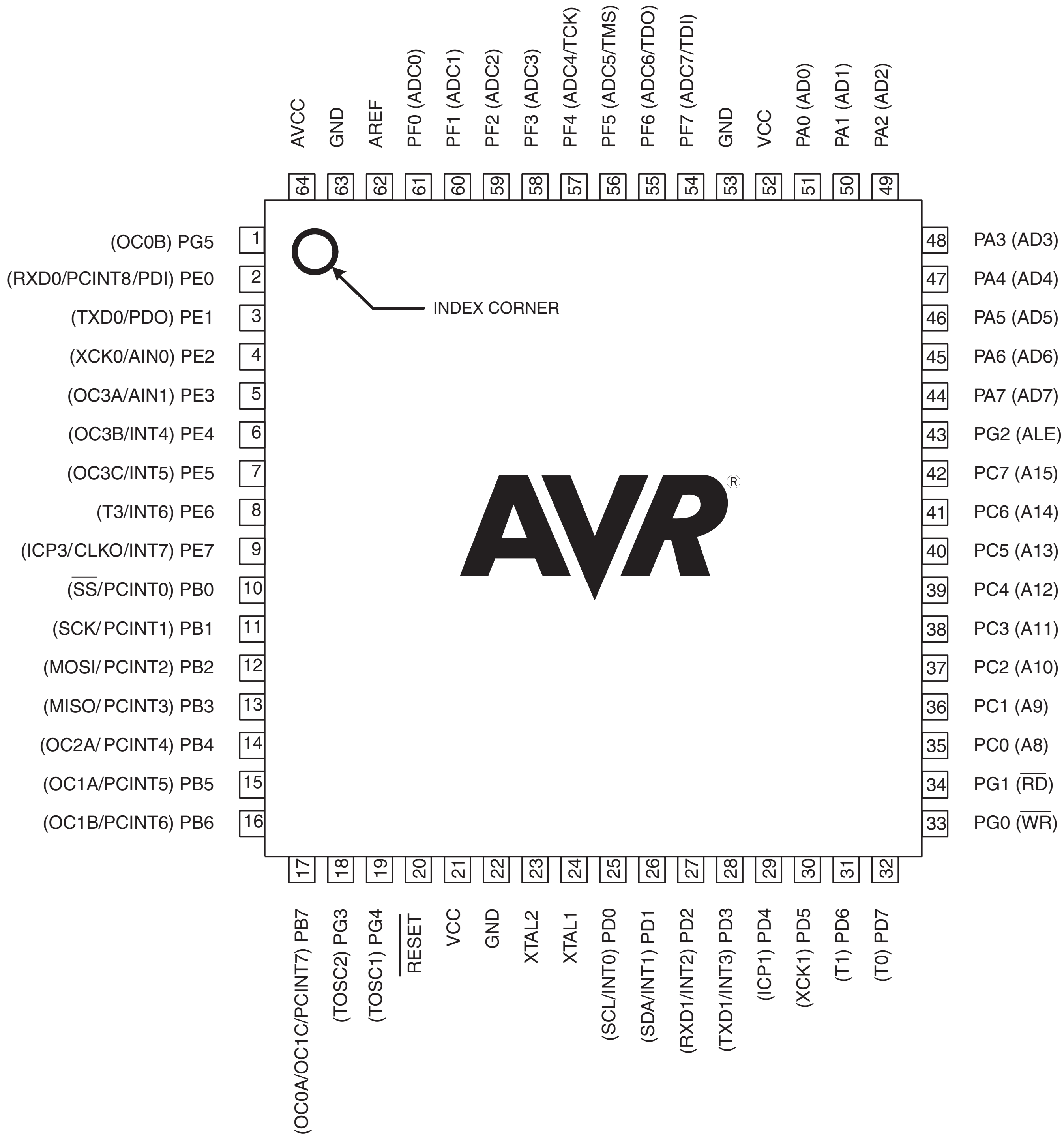


Table 1-1. CBGA-pinout ATmega640/1280/2560

	1	2	3	4	5	6	7	8	9	10
A	GND	AREF	PF0	PF2	PF5	PK0	PK3	PK6	GND	VCC
B	AVCC	PG5	PF1	PF3	PF6	PK1	PK4	PK7	PA0	PA2
C	PE2	PE0	PE1	PF4	PF7	PK2	PK5	PJ7	PA1	PA3
D	PE3	PE4	PE5	PE6	PH2	PA4	PA5	PA6	PA7	PG2
E	PE7	PH0	PH1	PH3	PH5	PJ6	PJ5	PJ4	PJ3	PJ2
F	VCC	PH4	PH6	PB0	PL4	PD1	PJ1	PJ0	PC7	GND
G	GND	PB1	PB2	PB5	PL2	PD0	PD5	PC5	PC6	VCC
H	PB3	PB4	RESET	PL1	PL3	PL7	PD4	PC4	PC3	PC2
J	PH7	PG3	PB6	PL0	XTAL2	PL6	PD3	PC1	PC0	PG1
K	PB7	PG4	VCC	GND	XTAL1	PL5	PD2	PD6	PD7	PG0

Note: The functions for each pin is the same as for the 100 pin packages shown in Figure 1-1 on page 2.

Figure 1-3. Pinout ATmega1281/2561



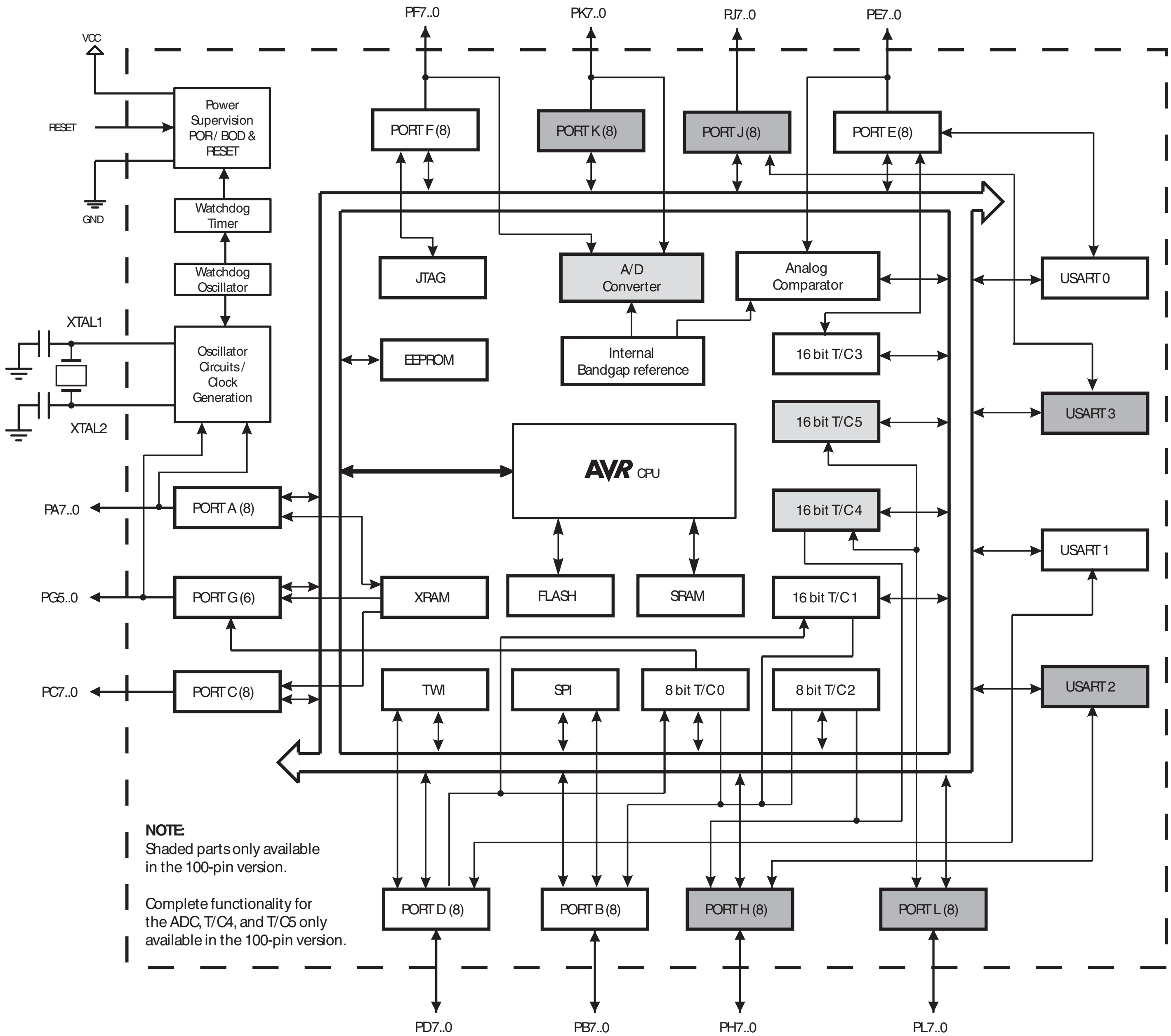
Note: The large center pad underneath the QFN/MLF package is made of metal and internally connected to GND. It should be soldered or glued to the board to ensure good mechanical stability. If the center pad is left unconnected, the package might loosen from the board.

2. Overview

The ATmega640/1280/1281/2560/2561 is a low-power CMOS 8-bit microcontroller based on the AVR enhanced RISC architecture. By executing powerful instructions in a single clock cycle, the ATmega640/1280/1281/2560/2561 achieves throughputs approaching 1 MIPS per MHz allowing the system designer to optimize power consumption versus processing speed.

2.1 Block Diagram

Figure 2-1. Block Diagram



The Atmel® AVR® core combines a rich instruction set with 32 general purpose working registers. All the 32 registers are directly connected to the Arithmetic Logic Unit (ALU), allowing two independent registers to be accessed in one single instruction executed in one clock cycle. The resulting architecture is more code efficient while achieving throughputs up to ten times faster than conventional CISC microcontrollers.

The ATmega640/1280/1281/2560/2561 provides the following features: 64K/128K/256K bytes of In-System Programmable Flash with Read-While-Write capabilities, 4Kbytes EEPROM, 8Kbytes SRAM, 54/86 general purpose I/O lines, 32 general purpose working registers, Real Time Counter (RTC), six flexible Timer/Counters with compare modes and PWM, four USARTs, a byte oriented 2-wire Serial Interface, a 16-channel, 10-bit ADC with optional differential input stage with programmable gain, programmable Watchdog Timer with Internal Oscillator, an SPI serial port, IEEE® std. 1149.1 compliant JTAG test interface, also used for accessing the On-chip Debug system and programming and six software selectable power saving modes. The Idle mode stops the CPU while allowing the SRAM, Timer/Counters, SPI port, and interrupt system to continue functioning. The Power-down mode saves the register contents but freezes the Oscillator, disabling all other chip functions until the next interrupt or Hardware Reset. In Power-save mode, the asynchronous timer continues to run, allowing the user to maintain a timer base while the rest of the device is sleeping. The ADC Noise Reduction mode stops the CPU and all I/O modules except Asynchronous Timer and ADC, to minimize switching noise during ADC conversions. In Standby mode, the Crystal/Resonator Oscillator is running while the rest of the device is sleeping. This allows very fast start-up combined with low power consumption. In Extended Standby mode, both the main Oscillator and the Asynchronous Timer continue to run.

Atmel offers the QTouch® library for embedding capacitive touch buttons, sliders and wheels functionality into AVR microcontrollers. The patented charge-transfer signal acquisition offersrobust sensing and includes fully debounced reporting of touch keys and includes Adjacent Key Suppression® (AKS®) technology for unambiguous detection of key events. The easy-to-use QTouch Suite toolchain allows you to explore, develop and debug your own touch applications.

The device is manufactured using the Atmel high-density nonvolatile memory technology. The On-chip ISP Flash allows the program memory to be reprogrammed in-system through an SPI serial interface, by a conventional non-volatile memory programmer, or by an On-chip Boot program running on the AVR core. The boot program can use any interface to download the application program in the application Flash memory. Software in the Boot Flash section will continue to run while the Application Flash section is updated, providing true Read-While-Write operation. By combining an 8-bit RISC CPU with In-System Self-Programmable Flash on a monolithic chip, the Atmel ATmega640/1280/1281/2560/2561 is a powerful microcontroller that provides a highly flexible and cost effective solution to many embedded control applications.

The ATmega640/1280/1281/2560/2561 AVR is supported with a full suite of program and system development tools including: C compilers, macro assemblers, program debugger/simulators, in-circuit emulators, and evaluation kits.

7. Register Summary

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Page
(0x1FF)	Reserved	-	-	-	-	-	-	-	-	
...	Reserved	-	-	-	-	-	-	-	-	
(0x13F)	Reserved									
(0x13E)	Reserved									
(0x13D)	Reserved									
(0x13C)	Reserved									
(0x13B)	Reserved									
(0x13A)	Reserved									
(0x139)	Reserved									
(0x138)	Reserved									
(0x137)	Reserved									
(0x136)	UDR3	USART3 I/O Data Register								page 218
(0x135)	UBRR3H	-	-	-	-	USART3 Baud Rate Register High Byte				page 222
(0x134)	UBRR3L	USART3 Baud Rate Register Low Byte								page 222
(0x133)	Reserved	-	-	-	-	-	-	-	-	
(0x132)	UCSR3C	UMSEL31	UMSEL30	UPM31	UPM30	USBS3	UCSZ31	UCSZ30	UCPOL3	page 235
(0x131)	UCSR3B	RXCIE3	TXCIE3	UDRIE3	RXEN3	TXEN3	UCSZ32	RXB83	TXB83	page 234
(0x130)	UCSR3A	RXC3	TXC3	UDRE3	FE3	DOR3	UPE3	U2X3	MPCM3	page 233
(0x12F)	Reserved	-	-	-	-	-	-	-	-	
(0x12E)	Reserved	-	-	-	-	-	-	-	-	
(0x12D)	OCR5CH	Timer/Counter5 - Output Compare Register C High Byte								page 160
(0x12C)	OCR5CL	Timer/Counter5 - Output Compare Register C Low Byte								page 160
(0x12B)	OCR5BH	Timer/Counter5 - Output Compare Register B High Byte								page 160
(0x12A)	OCR5BL	Timer/Counter5 - Output Compare Register B Low Byte								page 160
(0x129)	OCR5AH	Timer/Counter5 - Output Compare Register A High Byte								page 160
(0x128)	OCR5AL	Timer/Counter5 - Output Compare Register A Low Byte								page 160
(0x127)	ICR5H	Timer/Counter5 - Input Capture Register High Byte								page 161
(0x126)	ICR5L	Timer/Counter5 - Input Capture Register Low Byte								page 161
(0x125)	TCNT5H	Timer/Counter5 - Counter Register High Byte								page 158
(0x124)	TCNT5L	Timer/Counter5 - Counter Register Low Byte								page 158
(0x123)	Reserved	-	-	-	-	-	-	-	-	
(0x122)	TCCR5C	FOC5A	FOC5B	FOC5C	-	-	-	-	-	page 157
(0x121)	TCCR5B	ICNC5	ICES5	-	WGM53	WGM52	CS52	CS51	CS50	page 156
(0x120)	TCCR5A	COM5A1	COM5A0	COM5B1	COM5B0	COM5C1	COM5C0	WGM51	WGM50	page 154
(0x11F)	Reserved	-	-	-	-	-	-	-	-	
(0x11E)	Reserved	-	-	-	-	-	-	-	-	
(0x11D)	Reserved	-	-	-	-	-	-	-	-	
(0x11C)	Reserved	-	-	-	-	-	-	-	-	
(0x11B)	Reserved	-	-	-	-	-	-	-	-	
(0x11A)	Reserved	-	-	-	-	-	-	-	-	
(0x119)	Reserved	-	-	-	-	-	-	-	-	
(0x118)	Reserved	-	-	-	-	-	-	-	-	
(0x117)	Reserved	-	-	-	-	-	-	-	-	
(0x116)	Reserved	-	-	-	-	-	-	-	-	
(0x115)	Reserved	-	-	-	-	-	-	-	-	
(0x114)	Reserved	-	-	-	-	-	-	-	-	
(0x113)	Reserved	-	-	-	-	-	-	-	-	
(0x112)	Reserved	-	-	-	-	-	-	-	-	
(0x111)	Reserved	-	-	-	-	-	-	-	-	
(0x110)	Reserved	-	-	-	-	-	-	-	-	
(0x10F)	Reserved	-	-	-	-	-	-	-	-	
(0x10E)	Reserved	-	-	-	-	-	-	-	-	
(0x10D)	Reserved	-	-	-	-	-	-	-	-	
(0x10C)	Reserved	-	-	-	-	-	-	-	-	
(0x10B)	PORTL	PORTL7	PORTL6	PORTL5	PORTL4	PORTL3	PORTL2	PORTL1	PORTL0	page 100
(0x10A)	DDRL	DDL7	DDL6	DDL5	DDL4	DDL3	DDL2	DDL1	DDL0	page 100
(0x109)	PINL	PINL7	PINL6	PINL5	PINL4	PINL3	PINL2	PINL1	PINL0	page 100
(0x108)	PORTK	PORTK7	PORTK6	PORTK5	PORTK4	PORTK3	PORTK2	PORTK1	PORTK0	page 99
(0x107)	DDRK	DDK7	DDK6	DDK5	DDK4	DDK3	DDK2	DDK1	DDK0	page 99
(0x106)	PINK	PINK7	PINK6	PINK5	PINK4	PINK3	PINK2	PINK1	PINK0	page 99
(0x105)	PORTJ	PORTJ7	PORTJ6	PORTJ5	PORTJ4	PORTJ3	PORTJ2	PORTJ1	PORTJ0	page 99
(0x104)	DDRJ	DDJ7	DDJ6	DDJ5	DDJ4	DDJ3	DDJ2	DDJ1	DDJ0	page 99
(0x103)	PINJ	PINJ7	PINJ6	PINJ5	PINJ4	PINJ3	PINJ2	PINJ1	PINJ0	page 99
(0x102)	PORTH	PORTH7	PORTH6	PORTH5	PORTH4	PORTH3	PORTH2	PORTH1	PORTH0	page 98
(0x101)	DDRH	DDH7	DDH6	DDH5	DDH4	DDH3	DDH2	DDH1	DDH0	page 99

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Page
0x14 (0x34)	PORTG	-	-	PORTG5	PORTG4	PORTG3	PORTG2	PORTG1	PORTG0	page 98
0x13 (0x33)	DDRG	-	-	DDG5	DDG4	DDG3	DDG2	DDG1	DDG0	page 98
0x12 (0x32)	PING	-	-	PING5	PING4	PING3	PING2	PING1	PING0	page 98
0x11 (0x31)	PORTF	PORTF7	PORTF6	PORTF5	PORTF4	PORTF3	PORTF2	PORTF1	PORTF0	page 97
0x10 (0x30)	DDRF	DDF7	DDF6	DDF5	DDF4	DDF3	DDF2	DDF1	DDF0	page 98
0x0F (0x2F)	PINF	PINF7	PINF6	PINF5	PINF4	PINF3	PINF2	PINF1	PINF0	page 98
0x0E (0x2E)	PORTE	PORTE7	PORTE6	PORTE5	PORTE4	PORTE3	PORTE2	PORTE1	PORTE0	page 97
0x0D (0x2D)	DDRE	DDE7	DDE6	DDE5	DDE4	DDE3	DDE2	DDE1	DDE0	page 97
0x0C (0x2C)	PINE	PINE7	PINE6	PINE5	PINE4	PINE3	PINE2	PINE1	PINE0	page 98
0x0B (0x2B)	PORTD	PORTD7	PORTD6	PORTD5	PORTD4	PORTD3	PORTD2	PORTD1	PORTD0	page 97
0x0A (0x2A)	DDRD	DDD7	DDD6	DDD5	DDD4	DDD3	DDD2	DDD1	DDD0	page 97
0x09 (0x29)	PIND	PIND7	PIND6	PIND5	PIND4	PIND3	PIND2	PIND1	PIND0	page 97
0x08 (0x28)	PORTC	PORTC7	PORTC6	PORTC5	PORTC4	PORTC3	PORTC2	PORTC1	PORTC0	page 97
0x07 (0x27)	DDRC	DDC7	DDC6	DDC5	DDC4	DDC3	DDC2	DDC1	DDC0	page 97
0x06 (0x26)	PINC	PINC7	PINC6	PINC5	PINC4	PINC3	PINC2	PINC1	PINC0	page 97
0x05 (0x25)	PORTB	PORTB7	PORTB6	PORTB5	PORTB4	PORTB3	PORTB2	PORTB1	PORTB0	page 96
0x04 (0x24)	DDRB	DDB7	DDB6	DDB5	DDB4	DDB3	DDB2	DDB1	DDB0	page 96
0x03 (0x23)	PINB	PINB7	PINB6	PINB5	PINB4	PINB3	PINB2	PINB1	PINB0	page 96
0x02 (0x22)	PORTA	PORTA7	PORTA6	PORTA5	PORTA4	PORTA3	PORTA2	PORTA1	PORTA0	page 96
0x01 (0x21)	DDRA	DDA7	DDA6	DDA5	DDA4	DDA3	DDA2	DDA1	DDA0	page 96
0x00 (0x20)	PINA	PINA7	PINA6	PINA5	PINA4	PINA3	PINA2	PINA1	PINA0	page 96

Notes:

1. For compatibility with future devices, reserved bits should be written to zero if accessed. Reserved I/O memory addresses should never be written.
2. I/O registers within the address range $00 - $1F are directly bit-accessible using the SBI and CBI instructions. In these registers, the value of single bits can be checked by using the SBIS and SBIC instructions.
3. Some of the status flags are cleared by writing a logical one to them. Note that the CBI and SBI instructions will operate on all bits in the I/O register, writing a one back into any flag read as set, thus clearing the flag. The CBI and SBI instructions work with registers 0x00 to 0x1F only.
4. When using the I/O specific commands IN and OUT, the I/O addresses $00 - $3F must be used. When addressing I/O registers as data space using LD and ST instructions, $20 must be added to these addresses. The ATmega640/1280/1281/2560/2561 is a complex microcontroller with more peripheral units than can be supported within the 64 location reserved in Opcode for the IN and OUT instructions. For the Extended I/O space from $60 - $1FF in SRAM, only the ST/STS/STD and LD/LDS/LDD instructions can be used.

Mnemonics	Operands	Description	Operation	Flags	#Clocks
BRVC	k	Branch if Overflow Flag is Cleared	if (V = 0) then PC ← PC + k + 1	None	1/2
BRIE	k	Branch if Interrupt Enabled	if (I = 1) then PC ← PC + k + 1	None	1/2
BRID	k	Branch if Interrupt Disabled	if (I = 0) then PC ← PC + k + 1	None	1/2
BIT AND BIT-TEST INSTRUCTIONS					
SBI	P,b	Set Bit in I/O Register	I/O(P,b) ← 1	None	2
CBI	P,b	Clear Bit in I/O Register	I/O(P,b) ← 0	None	2
LSL	Rd	Logical Shift Left	Rd(n+1) ← Rd(n), Rd(0) ← 0	Z, C, N, V	1
LSR	Rd	Logical Shift Right	Rd(n) ← Rd(n+1), Rd(7) ← 0	Z, C, N, V	1
ROL	Rd	Rotate Left Through Carry	Rd(0)←C,Rd(n+1)← Rd(n),C←Rd(7)	Z, C, N, V	1
ROR	Rd	Rotate Right Through Carry	Rd(7)←C,Rd(n)← Rd(n+1),C←Rd(0)	Z, C, N, V	1
ASR	Rd	Arithmetic Shift Right	Rd(n) ← Rd(n+1), n=0..6	Z, C, N, V	1
SWAP	Rd	Swap Nibbles	Rd(3..0)←Rd(7..4),Rd(7..4)←Rd(3..0)	None	1
BSET	s	Flag Set	SREG(s) ← 1	SREG(s)	1
BCLR	s	Flag Clear	SREG(s) ← 0	SREG(s)	1
BST	Rr, b	Bit Store from Register to T	T ← Rr(b)	T	1
BLD	Rd, b	Bit load from T to Register	Rd(b) ← T	None	1
SEC		Set Carry	C ← 1	C	1
CLC		Clear Carry	C ← 0	C	1
SEN		Set Negative Flag	N ← 1	N	1
CLN		Clear Negative Flag	N ← 0	N	1
SEZ		Set Zero Flag	Z ← 1	Z	1
CLZ		Clear Zero Flag	Z ← 0	Z	1
SEI		Global Interrupt Enable	I ← 1	I	1
CLI		Global Interrupt Disable	I ← 0	I	1
SES		Set Signed Test Flag	S ← 1	S	1
CLS		Clear Signed Test Flag	S ← 0	S	1
SEV		Set Twos Complement Overflow.	V ← 1	V	1
CLV		Clear Twos Complement Overflow	V ← 0	V	1
SET		Set T in SREG	T ← 1	T	1
CLT		Clear T in SREG	T ← 0	T	1
SEH		Set Half Carry Flag in SREG	H ← 1	H	1
CLH		Clear Half Carry Flag in SREG	H ← 0	H	1
DATA TRANSFER INSTRUCTIONS					
MOV	Rd, Rr	Move Between Registers	Rd ← Rr	None	1
MOVW	Rd, Rr	Copy Register Word	Rd+1:Rd ← Rr+1:Rr	None	1
LDI	Rd, K	Load Immediate	Rd ← K	None	1
LD	Rd, X	Load Indirect	Rd ← (X)	None	2
LD	Rd, X+	Load Indirect and Post-Inc.	Rd ← (X), X ← X + 1	None	2
LD	Rd, - X	Load Indirect and Pre-Dec.	X ← X - 1, Rd ← (X)	None	2
LD	Rd, Y	Load Indirect	Rd ← (Y)	None	2
LD	Rd, Y+	Load Indirect and Post-Inc.	Rd ← (Y), Y ← Y + 1	None	2
LD	Rd, - Y	Load Indirect and Pre-Dec.	Y ← Y - 1, Rd ← (Y)	None	2
LDD	Rd,Y+q	Load Indirect with Displacement	Rd ← (Y + q)	None	2
LD	Rd, Z	Load Indirect	Rd ← (Z)	None	2
LD	Rd, Z+	Load Indirect and Post-Inc.	Rd ← (Z), Z ← Z+1	None	2
LD	Rd, -Z	Load Indirect and Pre-Dec.	Z ← Z - 1, Rd ← (Z)	None	2
LDD	Rd, Z+q	Load Indirect with Displacement	Rd ← (Z + q)	None	2
LDS	Rd, k	Load Direct from SRAM	Rd ← (k)	None	2
ST	X, Rr	Store Indirect	(X) ← Rr	None	2
ST	X+, Rr	Store Indirect and Post-Inc.	(X) ← Rr, X ← X + 1	None	2
ST	- X, Rr	Store Indirect and Pre-Dec.	X ← X - 1, (X) ← Rr	None	2
ST	Y, Rr	Store Indirect	(Y) ← Rr	None	2
ST	Y+, Rr	Store Indirect and Post-Inc.	(Y) ← Rr, Y ← Y + 1	None	2
ST	- Y, Rr	Store Indirect and Pre-Dec.	Y ← Y - 1, (Y) ← Rr	None	2
STD	Y+q,Rr	Store Indirect with Displacement	(Y + q) ← Rr	None	2
ST	Z, Rr	Store Indirect	(Z) ← Rr	None	2
ST	Z+, Rr	Store Indirect and Post-Inc.	(Z) ← Rr, Z ← Z + 1	None	2
ST	-Z, Rr	Store Indirect and Pre-Dec.	Z ← Z - 1, (Z) ← Rr	None	2
STD	Z+q,Rr	Store Indirect with Displacement	(Z + q) ← Rr	None	2
STS	k, Rr	Store Direct to SRAM	(k) ← Rr	None	2
LPM		Load Program Memory	R0 ← (Z)	None	3
LPM	Rd, Z	Load Program Memory	Rd ← (Z)	None	3
LPM	Rd, Z+	Load Program Memory and Post-Inc	Rd ← (Z), Z ← Z+1	None	3
ELPM		Extended Load Program Memory	R0 ← (RAMPZ:Z)	None	3
ELPM	Rd, Z	Extended Load Program Memory	Rd ← (RAMPZ:Z)	None	3
ELPM	Rd, Z+	Extended Load Program Memory	Rd ← (RAMPZ:Z), RAMPZ:Z ←RAMPZ:Z+1	None	3
SPM		Store Program Memory	(Z) ← R1:R0	None	-
IN	Rd, P	In Port	Rd ← P	None	1

9. Ordering Information

9.1 ATmega640

Speed [MHz][2]	Power Supply	Ordering Code	Package[1][3]	Operation Range
8	1.8 - 5.5V	ATmega640V-8AU ATmega640V-8AUR[4] ATmega640V-8CU ATmega640V-8CUR[4]	100A 100A 100C1 100C1	Industrial (-40°C to 85°C)
16	2.7 - 5.5V	ATmega640-16AU ATmega640-16AUR[4] ATmega640-16CU ATmega640-16CUR[4]	100A 100A 100C1 100C1	

Notes:
1. This device can also be supplied in wafer form. Contact your local Atmel sales office for detailed ordering information and minimum quantities.
2. See "Speed Grades" on page 357.
3. Pb-free packaging, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
4. Tape & Reel.

Package Type	
100A	100-lead, Thin (1.0mm) Plastic Gull Wing Quad Flat Package (TQFP)
100C1	100-ball, Chip Ball Grid Array (CBGA)

9.3 ATmega1281

Speed [MHz][2]	Power Supply	Ordering Code	Package[1][3]	Operation Range
8	1.8 - 5.5V	ATmega1281V-8AU ATmega1281V-8AUR[4] ATmega1281V-8MU ATmega1281V-8MUR[4]	64A 64A 64M2 64M2	Industrial (-40°C to 85°C)
16	2.7 - 5.5V	ATmega1281-16AU ATmega1281-16AUR[4] ATmega1281-16MU ATmega1281-16MUR[4]	64A 64A 64M2 64M2	

Notes:
1. This device can also be supplied in wafer form. Contact your local Atmel sales office for detailed ordering information and minimum quantities.
2. See "Speed Grades" on page 357.
3. Pb-free packaging, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
4. Tape & Reel.

Package Type	
64A	64-lead, Thin (1.0mm) Plastic Gull Wing Quad Flat Package (TQFP)
64M2	64-pad, 9mm × 9mm × 1.0mm Body, Quad Flat No-lead/Micro Lead Frame Package (QFN/MLF)

9.4 ATmega2560

Speed [MHz][2]	Power Supply	Ordering Code	Package[1][3]	Operation Range
8	1.8V - 5.5V	ATmega2560V-8AU ATmega2560V-8AUR[4] ATmega2560V-8CU ATmega2560V-8CUR[4]	100A 100A 100C1 100C1	Industrial (-40°C to 85°C)
16	4.5V - 5.5V	ATmega2560-16AU ATmega2560-16AUR[4] ATmega2560-16CU ATmega2560-16CUR[4]	100A 100A 100C1 100C1	

Notes:
1. This device can also be supplied in wafer form. Contact your local Atmel sales office for detailed ordering information and minimum quantities.
2. See "Speed Grades" on page 357.
3. Pb-free packaging, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
4. Tape & Reel.

Package Type	
100A	100-lead, Thin (1.0mm) Plastic Gull Wing Quad Flat Package (TQFP)
100C1	100-ball, Chip Ball Grid Array (CBGA)

9.5 ATmega2561

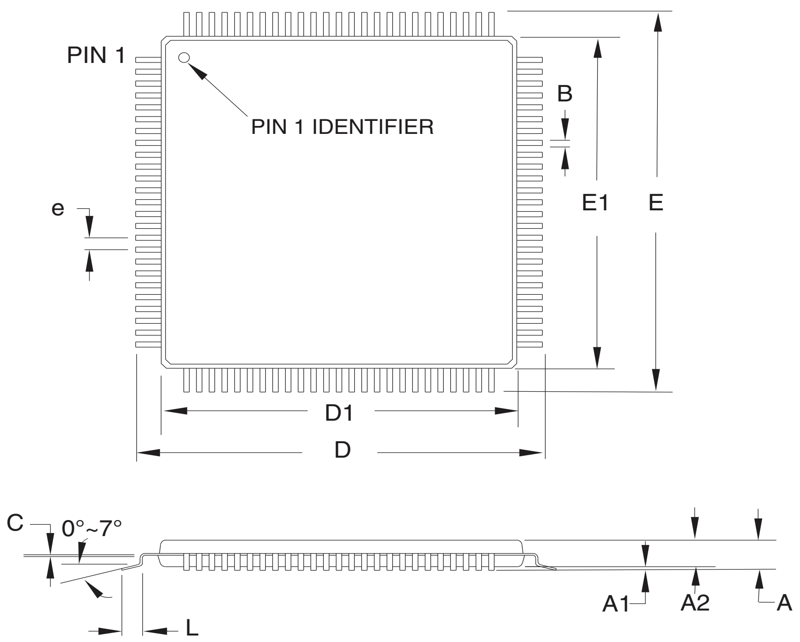
Speed [MHz][2]	Power Supply	Ordering Code	Package[1][3]	Operation Range
8	1.8V - 5.5V	ATmega2561V-8AU ATmega2561V-8AUR[4] ATmega2561V-8MU ATmega2561V-8MUR[4]	64A 64A 64M2 64M2	Industrial (-40°C to 85°C)
16	4.5V - 5.5V	ATmega2561-16AU ATmega2561-16AUR[4] ATmega2561-16MU ATmega2561-16MUR[4]	64A 64A 64M2 64M2	

Notes:
1. This device can also be supplied in wafer form.Contact your local Atmel sales office for detailed ordering information and minimum quantities.
2. See "Speed Grades" on page 357.
3. Pb-free packaging, complies to the European Directive for Restriction of Hazardous Substances (RoHS directive). Also Halide free and fully Green.
4. Tape & Reel.

Package Type	
64A	64-lead, Thin (1.0mm) Plastic Gull Wing Quad Flat Package (TQFP)
64M2	64-pad, 9mm × 9mm × 1.0mm Body, Quad Flat No-lead/Micro Lead Frame Package (QFN/MLF)

10. Packaging Information

10.1 100A



COMMON DIMENSIONS
(Unit of Measure = mm)

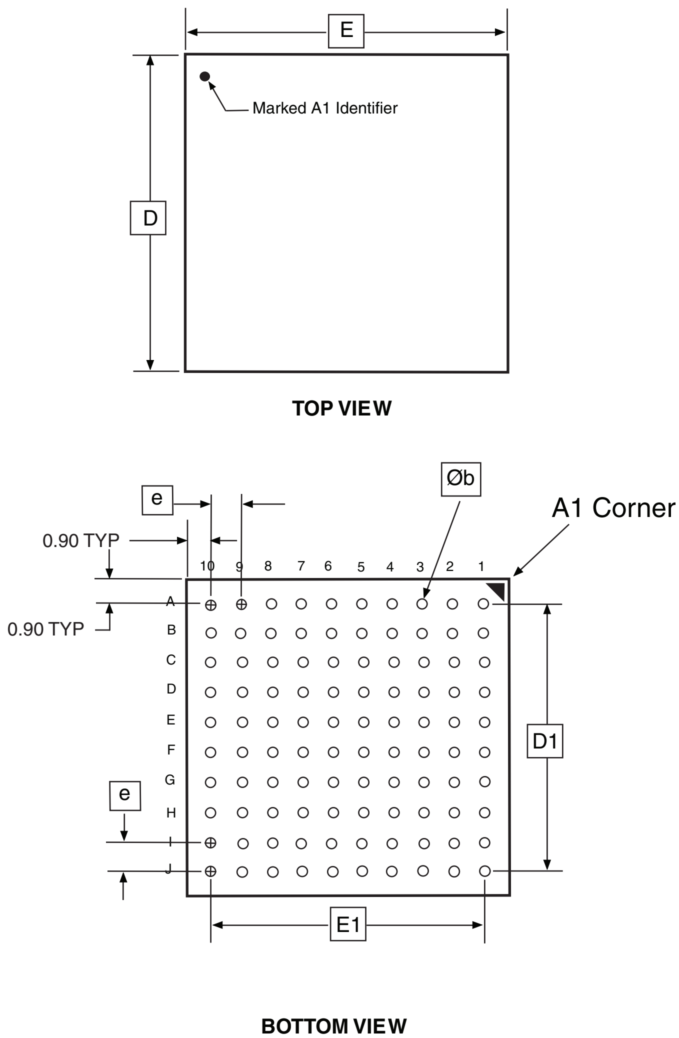
SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05	–	0.15	
A2	0.95	1.00	1.05	
D	15.75	16.00	16.25	
D1	13.90	14.00	14.10	Note 2
E	15.75	16.00	16.25	
E1	13.90	14.00	14.10	Note 2
B	0.17	–	0.27	
C	0.09	–	0.20	
L	0.45	–	0.75	
e	0.50 TYP			

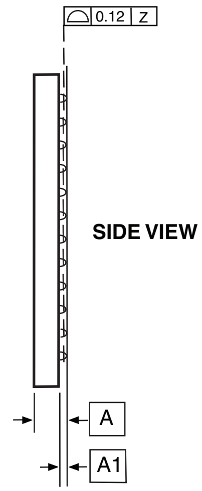
Notes:
1. This package conforms to JEDEC reference MS-026, Variation AED.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.08 mm maximum.

2010-10-20

	TITLE	DRAWING NO.	REV.
Atmel **Package Drawing Contact:** **packagedrawings@atmel.com**	**100A**, 100-lead, 14 x 14 mm Body Size, 1.0 mm Body Thickness, 0.5 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	100A	D

10.2 100C1





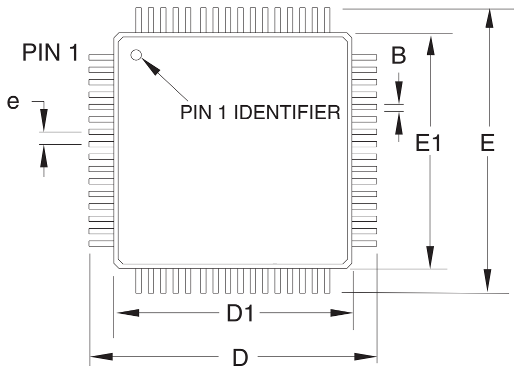
COMMON DIMENSIONS
(Unit of Measure = mm)

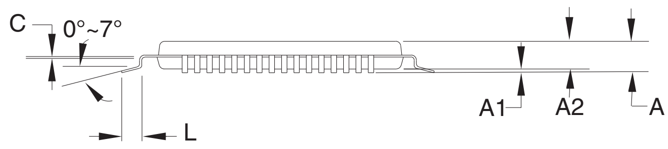
SYMBOL	MIN	NOM	MAX	NOTE
A	1.10	–	1.20	
A1	0.30	0.35	0.40	
D	8.90	9.00	9.10	
E	8.90	9.00	9.10	
D1	7.10	7.20	7.30	
E1	7.10	7.20	7.30	
Øb	0.35	0.40	0.45	
e	0.80 TYP			

5/25/06

	TITLE	DRAWING NO.	REV.
Atmel 2325 Orchard Parkway San Jose, CA 95131	**100C1**, 100-ball, 9 x 9 x 1.2 mm Body, Ball Pitch 0.80 mm Chip Array BGA Package (CBGA)	100C1	A

10.3 64A





COMMON DIMENSIONS
(Unit of measure = mm)

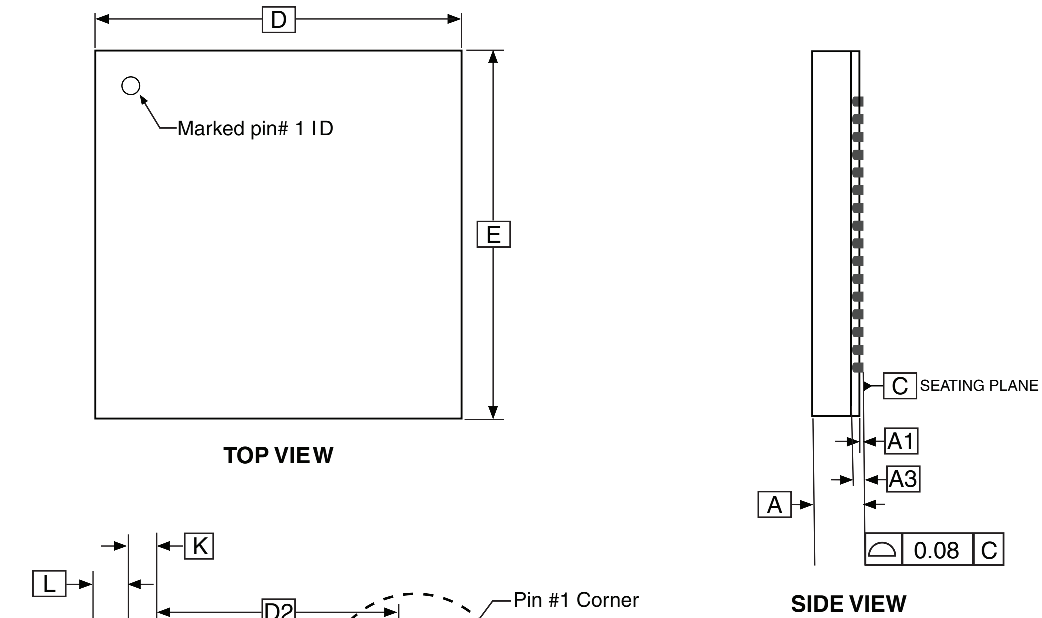
SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05	–	0.15	
A2	0.95	1.00	1.05	
D	15.75	16.00	16.25	
D1	13.90	14.00	14.10	Note 2
E	15.75	16.00	16.25	
E1	13.90	14.00	14.10	Note 2
B	0.30	–	0.45	
C	0.09	–	0.20	
L	0.45	–	0.75	
e	0.80 TYP			

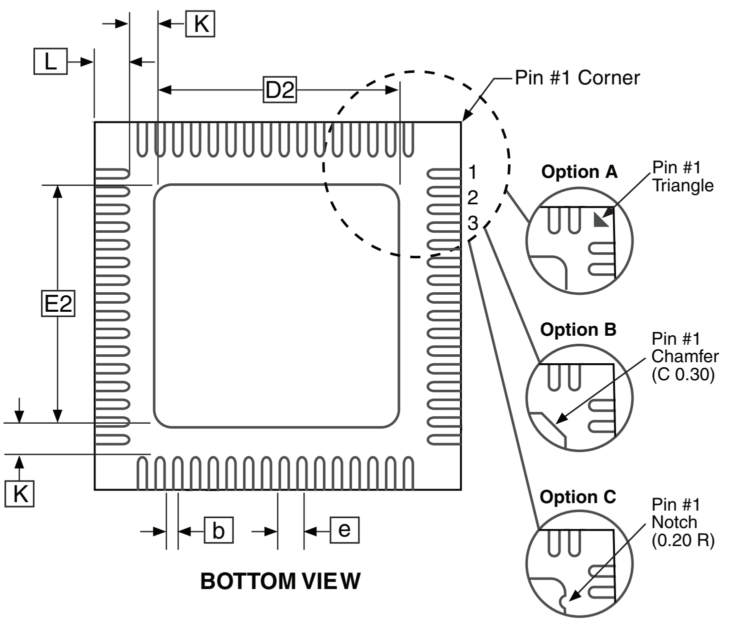
Notes:
1. This package conforms to JEDEC reference MS-026, Variation AEB.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

2010-10-20

	TITLE	DRAWING NO.	REV.
Atmel 2325 Orchard Parkway San Jose, CA 95131	**64A,** 64-lead, 14 x 14mm Body Size, 1.0mm Body Thickness, 0.8mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	64A	C

10.4 64M2





COMMON DIMENSIONS
(Unit of measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.80	0.90	1.00	
A1	–	0.02	0.05	
A3		0.20 REF		
b	0.18	0.25	0.30	
D	8.90	9.00	9.10	
D2	7.50	7.65	7.80	
E	8.90	9.00	9.10	
E2	7.50	7.65	7.80	
e		0.50 BSC		
L	0.35	0.40	0.45	
K	0.20	0.27	0.40	

Notes: 1. JEDEC Standard MO-220, (SAW Singulation) fig . 1, VMMD.
2. Dimension and tolerance conform to ASMEY14.5M-1994.

2014-02-12

Atmel 2325 Orchard Parkway San Jose, CA 95131	TITLE **64M2**, 64-pad, 9 x 9 x 1.0mm Bod y, Lead Pitch 0.50mm , 7.65mm Exposed Pad, Micro Lead Frame Package (MLF)	DRAWING NO. 64M2	REV. E

11. Errata

11.1 ATmega640 rev. B

- **Inaccurate ADC conversion in differential mode with 200× gain**
- **High current consumption in sleep mode**

1. **Inaccurate ADC conversion in differential mode with 200× gain**
   With AVCC <3.6V, random conversions will be inaccurate. Typical absolute accuracy may reach 64 LSB.

   Problem Fix/Workaround
   None.

2. **High current consumption in sleep mode**
   If a pending interrupt cannot wake the part up from the selected sleep mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

   Problem Fix/Workaround
   Before entering sleep, interrupts not used to wake the part from the sleep mode should be disabled.

11.2 ATmega640 rev. A

- **Inaccurate ADC conversion in differential mode with 200× gain**
- **High current consumption in sleep mode**

1. **Inaccurate ADC conversion in differential mode with 200× gain**
   With AVCC <3.6V, random conversions will be inaccurate. Typical absolute accuracy may reach 64 LSB.

   Problem Fix/Workaround
   None.

2. **High current consumption in sleep mode**
   If a pending interrupt cannot wake the part up from the selected sleep mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

   Problem Fix/Workaround
   Before entering sleep, interrupts not used to wake the part from the sleep mode should be disabled.

11.3 ATmega1280 rev. B

- **High current consumption in sleep mode**

1. **High current consumption in sleep mode**
   If a pending interrupt cannot wake the part up from the selected sleep mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

   Problem Fix/Workaround
   Before entering sleep, interrupts not used to wake the part from the sleep mode should be disabled.

11.4 ATmega1280 rev. A

- **Inaccurate ADC conversion in differential mode with 200× gain**
- **High current consumption in sleep mode**

1. **Inaccurate ADC conversion in differential mode with 200× gain**
   With AVCC <3.6V, random conversions will be inaccurate. Typical absolute accuracy may reach 64 LSB.

5. **IN/OUT instructions may be executed twice when Stack is in external RAM**
   If either an IN or an OUT instruction is executed directly before an interrupt occurs and the stack pointer is located in external ram, the instruction will be executed twice. In some cases this will cause a problem, for example:

   - If reading SREG it will appear that the I-flag is cleared.

   - If writing to the PIN registers, the port will toggle twice.

   - If reading registers with interrupt flags, the flags will appear to be cleared.

   Problem Fix/Workaround
   There are two application workarounds, where selecting one of them, will be omitting the issue:

   - Replace IN and OUT with LD/LDS/LDD and ST/STS/STD instructions.

   - Use internal RAM for stack pointer.

6. **EEPROM read from application code does not work in Lock Bit Mode 3**
   When the Memory Lock Bits LB2 and LB1 are programmed to mode 3, EEPROM read does not work from the application code.

   Problem Fix/Workaround
   Do not set Lock Bit Protection Mode 3 when the application code needs to read from EEPROM.

11.13 ATmega2561 rev. F

- **ADC differential input amplification by 46dB (200x) not functional**

1. **ADC differential input amplification by 46dB (200x) not functional**
   Problem Fix/Workaround
   None.

11.14 ATmega2561 rev. E

No known errata.

11.15 ATmega2561 rev. D

Not sampled.

11.16 ATmega2561 rev. C

- **High current consumption in sleep mode.**

1. **High current consumption in sleep mode**
   If a pending interrupt cannot wake the part up from the selected sleep mode, the current consumption will increase during sleep when executing the SLEEP instruction directly after a SEI instruction.

   Problem Fix/Workaround
   Before entering sleep, interrupts not used to wake the part from the sleep mode should be disabled.

11.17 ATmega2561 rev. B

Not sampled.

11.18 ATmega2561 rev. A

- **Non-Read-While-Write area of flash not functional**
- **Part does not work under 2.4 Volts**
- **Incorrect ADC reading in differential mode**
- **Internal ADC reference has too low value**
- **IN/OUT instructions may be executed twice when Stack is in external RAM**
- **EEPROM read from application code does not work in Lock Bit Mode 3**

1. Non-Read-While-Write area of flash not functional

The Non-Read-While-Write area of the flash is not working as expected. The problem is related to the speed of the part when reading the flash of this area.

Problem Fix/Workaround

- Only use the first 248K of the flash.

- If boot functionality is needed, run the code in the Non-Read-While-Write area at maximum 1/4th of the maximum frequency of the device at any given voltage. This is done by writing the CLKPR register before entering the boot section of the code.

2. Part does not work under 2.4 volts

The part does not execute code correctly below 2.4 volts.

Problem Fix/Workaround

Do not use the part at voltages below 2.4 volts.

3. Incorrect ADC reading in differential mode

The ADC has high noise in differential mode. It can give up to 7 LSB error.

Problem Fix/Workaround

Use only the 7 MSB of the result when using the ADC in differential mode.

4. Internal ADC reference has too low value

The internal ADC reference has a value lower than specified.

Problem Fix/Workaround

- Use AVCC or external reference.

- The actual value of the reference can be measured by applying a known voltage to the ADC when using the internal reference. The result when doing later conversions can then be calibrated.

5. IN/OUT instructions may be executed twice when Stack is in external RAM

If either an IN or an OUT instruction is executed directly before an interrupt occurs and the stack pointer is located in external ram, the instruction will be executed twice. In some cases this will cause a problem, for example:

- If reading SREG it will appear that the I-flag is cleared.

- If writing to the PIN registers, the port will toggle twice.

- If reading registers with interrupt flags, the flags will appear to be cleared.

Problem Fix/Workaround

There are two application workarounds, where selecting one of them, will be omitting the issue:

- Replace IN and OUT with LD/LDS/LDD and ST/STS/STD instructions.

- Use internal RAM for stack pointer.

6. **EEPROM read from application code does not work in Lock Bit Mode 3**
   When the Memory Lock Bits LB2 and LB1 are programmed to mode 3, EEPROM read does not work from the application code.

   Problem Fix/Workaround
   Do not set Lock Bit Protection Mode 3 when the application code needs to read from EEPROM.

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